



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

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PRINTED CIRCUIT BOARDS

01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

06 229 FR4 105 L41.140 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_229_FR4_105_L41.140_p10

| Layers | in μ | Material | Build-Up | Assembly |
|----------|-----------|----------|--------------------------------|----------|
| Layer-1 | 105 μ | Copper | | A1 |
| | 100 μ | Prepreg | (100 μ PrePreg-Type: 2125) | |
| | 100 μ | Prepreg | | |
| Layer-2 | 140 μ | Copper | | |
| | 410 μ | L-FR4 | | |
| Layer-3 | 140 μ | Copper | | |
| | 100 μ | Prepreg | | |
| | 100 μ | Prepreg | | |
| | 100 μ | Prepreg | | |
| Layer-4 | 140 μ | Copper | | |
| | 410 μ | L-FR4 | | |
| Layer-5 | 140 μ | Copper | | |
| | 100 μ | Prepreg | | |
| | 100 μ | Prepreg | | |
| Layer-99 | 105 μ | Copper | | B |

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